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Atty. Dkt. No. 039153-0457 (G1162)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lopatin et al.
Title: METHOD OF USING TERNARY
COPPER ALLOY TO OBTAIN A
LOW RESISTANCE AND LARGE
GRAIN SIZE INTERCONNECT
Appl. No.: 09/994,395
Filing Date: 11/26/2001
Examiner: Unknown
Art Unit: Unknown

CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below. <u>CHRIS ESCAYAILLE</u> (Printed Name) <u>Chris Escayaille</u> (Signature) <u>9-23-02</u> (Date of Deposit)

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

ATTENTION: DRAWING REVIEW BRANCH

Sir:

Transmitted herewith are the formal drawings (9 sheets, Figures 1-7) for the above-identified application. The Official Draftsperson is respectfully requested to approve these drawings for entry into the application.

Respectfully submitted,

Date Sept. 23, 2002

By

FOLEY & LARDNER
777 East Wisconsin Avenue
Milwaukee, Wisconsin 53202-5367
Telephone: (414) 297-5728
Facsimile: (414) 297-4900

Paul S. Hunter
Attorney for Applicant
Registration No. 44,787